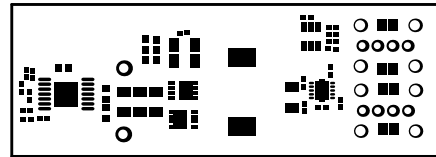
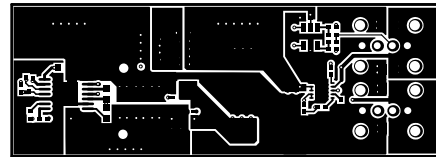


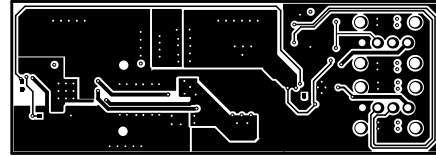
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/22/2015 5:49:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/22/2015 5:49:57 PM	TEXAS INSTRUMENTS	



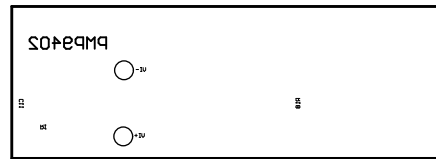
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/22/2015 5:49:57 PM	TEXAS INSTRUMENTS	



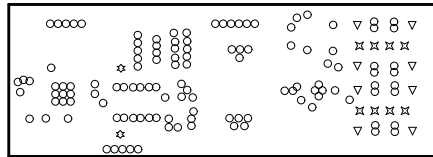
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/22/2015 5:49:58 PM	TEXAS INSTRUMENTS	



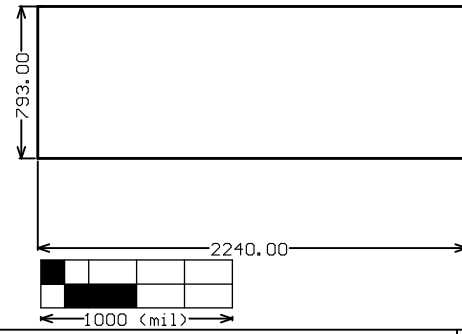
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/22/2015 5:49:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/22/2015 5:49:59 PM	TEXAS INSTRUMENTS	



		Symbol	Hit Count	Tool Size	Plated	Hole Type
ALL ARTWORK VIEWED FROM TOP SIDE		o	123	11mil (0.279mm)	PTH	Round
BOARD #: PMP9402		x	8	37.402mil (0.95mm)	PTH	Round
REV: 1		v	8	49.213mil (1.25mm)	PTH	Round
LAYER NAME = Drill Drawing			141 Total	53.937mil (1.37mm)	PTH	Round
PLOT NAME = Drill Drawing		GENERATED : 4/22/2015 5:50:00 PM		TEXAS INSTRUMENTS		



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9402	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/22/2015 5:50:01 PM	TEXAS INSTRUMENTS	

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